



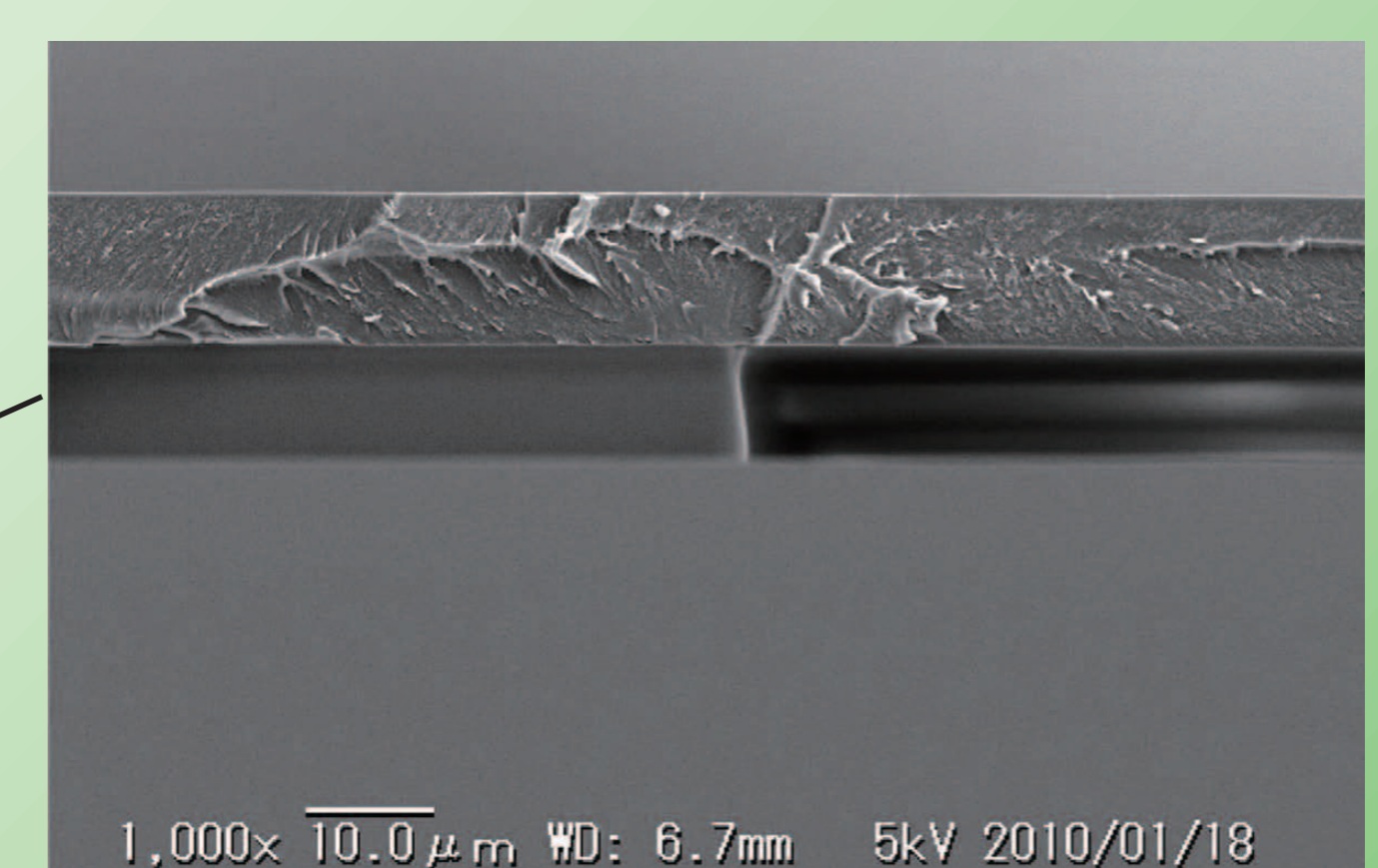
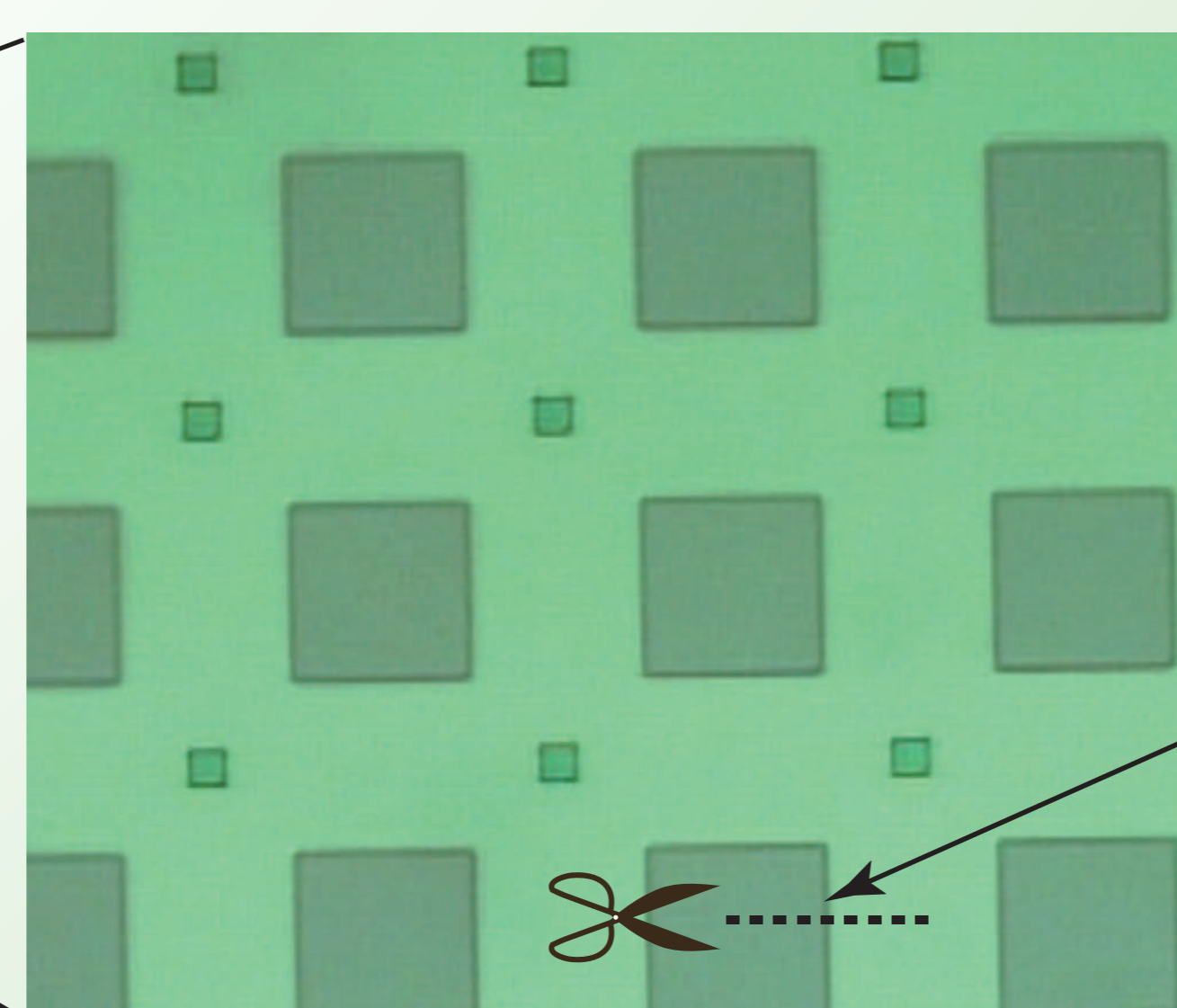
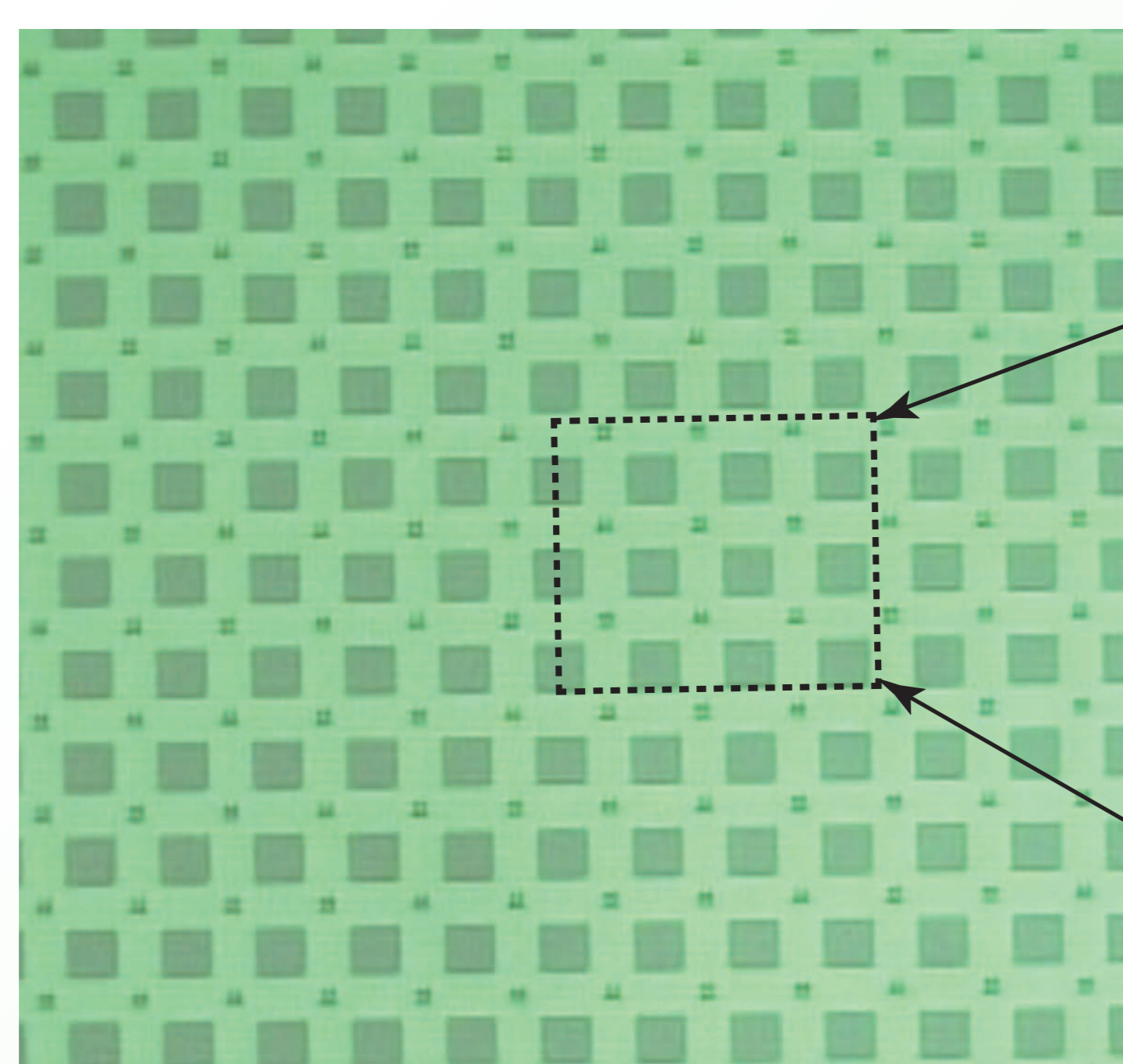
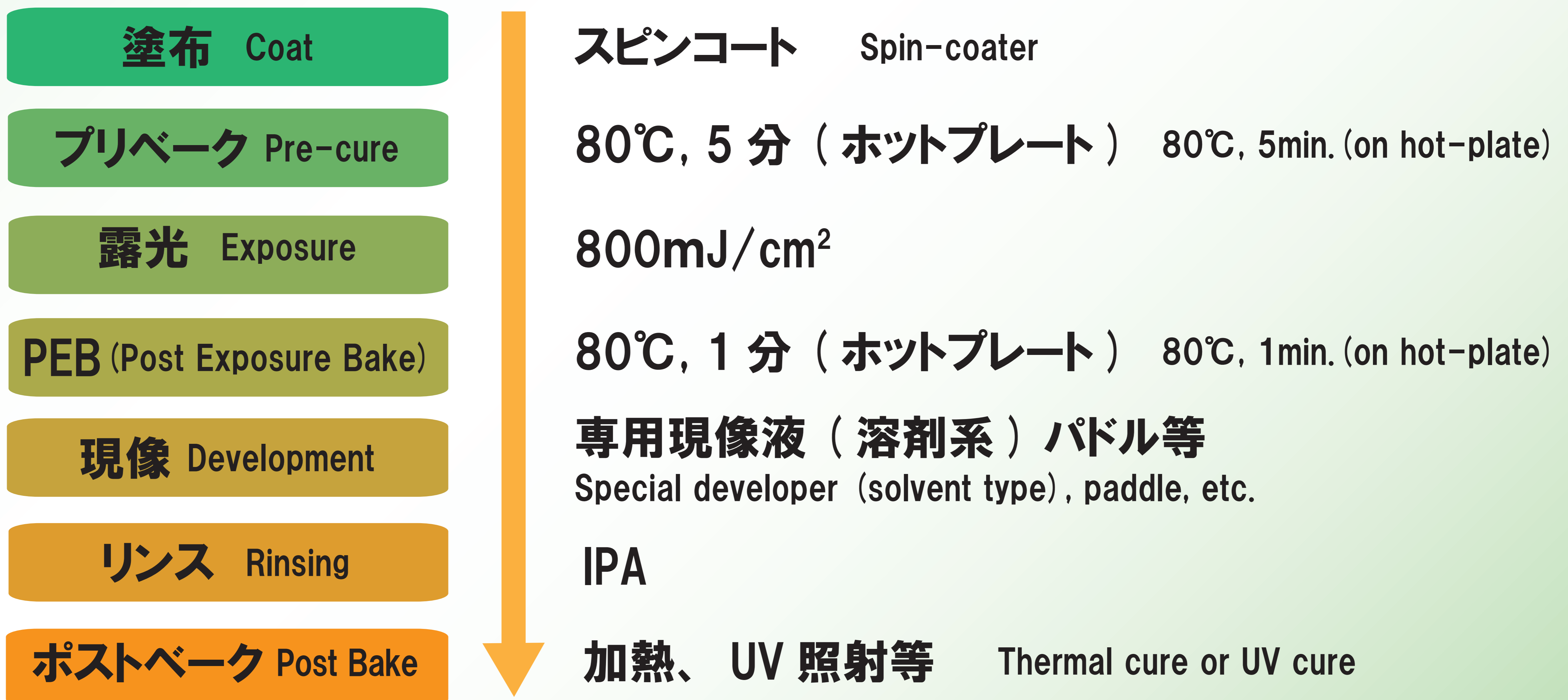
# フォト成型樹脂 Photoimageable Molding Resin

## ネガ型化学増幅型オキセタン系の成型用樹脂

Negative type, chemical-amplified oxsetane molding resin

- **i線 (365nm) を中心とした感光域** Photo-sensitive spectrum (center : i-line 365nm)
- **極性の低い溶剤を使用しているため未硬化樹脂の上に形成可能**  
Low-polarity solvent for use on surface of uncured resin
- **エポキシ系に比較して、高分子量化するため強靱な成型物が得られる**  
Tougher molding material due to higher molecular mass compared with epoxy cure type
- **低金属イオン (1ppm 未満)** Low metal ion (under 1ppm)
- **耐熱性、耐薬品性に優れる** Excellent heat resistance and chemical resistance

## プロセス Process



TAIYO INK MFG. CO., LTD.